

Serial No.: 09/928,314

**REMARKS**

No new matter has been added. The Applicant again requests entry of the amendments as set forth in the Appendices hereto prior to examination of the application on the merits.

Respectfully submitted,



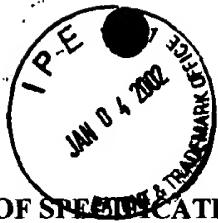
Brick G. Power  
Registration No. 38,581  
Attorney for Applicant  
TRASKBRITT  
P. O. Box 2550  
Salt Lake City, Utah 84110-2550  
Telephone: (801) 532-1922

Date: October 17, 2001

BGP/dn:blh

NA22692688.5PRELIM.AMD

Enclosures:   Version of Specification with Markings to Show Changes Made  
                  Version of Claims with Markings to Show Changes Made



Serial No.: 09/928,314

**VERSION OF SPECIFICATION WITH MARKINGS TO SHOW CHANGES MADE**

Please replace the Abstract of the Disclosure as follows:

**ABSTRACT OF THE DISCLOSURE**

A laser marking apparatus and method for marking the surface of a semiconductor chip are described herein. A laser beam is directed to a location on the surface of the chip where a laser reactive material, such as a pigment containing epoxy, is present. The heat associated with the laser beam causes the laser reactive material to fuse to the surface of the chip, creating a visibly distinct mark in contrast to the rest of the surface of the chip. Only reactive material contacted by the laser fuses to the chip surface[,] and the remaining residue on the non-irradiated portion can be readily removed.

RECEIVED  
JAN 25 2002  
10 2800 MAIL ROOM

**VERSION OF CLAIMS WITH MARKINGS TO SHOW CHANGES MADE**

5. (Amended) The method of claim 1, wherein said marking comprises:  
providing energy reactive marking material over [surfaces]a surface of at least [those chips]one  
chip which [are]is characterized for use; and  
exposing at least selected portions of at least one of said surface and said energy reactive marking  
material to energy to form a mark on said surface.

13. (Amended) A method for producing semiconductor chips, comprising:  
providing at least one semiconductor chip which has been characterized as suitable for use and at  
least one semiconductor chip which has been characterized as unsuitable for use; and  
marking with identifying indicia only [the]said at least one semiconductor chip which has been  
characterized as suitable for use.

22. (Amended) The method of claim 21, further comprising removing said identifying  
indicia which does not substantially match said acceptable identifying indicia model from said  
rejected at least one semiconductor chip which has been characterized as suitable for use.

23. (Amended) The method of claim 22, further comprising remarking said rejected at  
least one semiconductor chip which has been characterized as suitable for use.